

12th International Workshop on Beam Injection Assessment of Microstructures in Semiconductors つくば 2014 年 06月

Formation of dislocation pile-ups and subgrain boundaries in multicrystalline silicon

Daniel Oriwol, <u>Hartmut S. Leipner</u>, Andreas N. Danilewsky, Lamine Sylla, Winfried Seifert, Martin Kittler, Jan Bauer











Martin-Luther-Universität Halle–Wittenberg

Universität Freiburg

Joint Lab IHP/BTU

MPI Halle

© All rights reserved 2014

Introduction

Multicrystalline Silicon grown by directional solidification is the mainstream in PV industry due to low cost of ownership and high throughput.

Microwave-detected photoconductivity



Wafers

Ingot

Bricks

Dislocation issues in mc Si

Minority carrier lifetime vs etch pit density

Carrier lifetime, BB PL, defect PL and dislocation density



[Arafune 2006]

Dislocations and solar-cell efficiency



Etched wafer surface



Typical dislocation distribution

Evolution of dislocations



- Dislocation clusters mainly generated at grain boundaries
- Atomistic source of the spontaneous dislocation generation not known

Change of defect distribution in the ingot





Growth direction

Grain orientation effect



Grain orientation $\langle uvw \rangle$

Dislocation arrangements



EPD ~ 1×10⁵ cm⁻²

EPD 2×10⁵ cm⁻²

Too low for dislocation pile-ups/subgrain boundaries

TEM of subgrain boundaries



- Dislocation distance $h = 5 \dots 900$ nm
- A preferred alignment dislocation arrangements exist, but not in relation to the orientation of the grains.

White beam X-ray topography (WB-XRT)



Interpretation of WB-XRT contrasts



Splitting of the reflection due to subgrain boundary

Splitting of reflections



D Oriwol et al: Acta Mater 61 (2013) 6903.

Tilt of subgrains



Simulation with LauePT

5-5384 7 -1 -5 20 - 23 - 1 - 3 2-46 1-35 1-3 22-4 0-26 02-2 13-3 -228 -35 -260-355

Simulation, rotated by 3° about y

Subgrains are tilted about an axis parallel to the growth direction

Relation of tilt and subgrain boundaries



- Tilt = 0.07° (d6) ... 0.3° (d4) \rightarrow dislocation distance h = 800 ... 30 nm
- The increase in dislocation density as a function of ingot heigth leads to a continuous generation of subgrain boundaries.

EBIC and X-ray topography



1 mm

EBIC and **EBSD**

EBIC at 77 K



Electron backscatter difraction



- Subgrain boundaries with tilt angles > 0.4° electrically active
- Large-angle grain boundaries with no EBIC contrast at RT
 - \rightarrow other reasons for electrical activation (no dislocation model)

Dark lock-in thermography (DLIT)



Correlation analysis



Conclusions



Evolution of dislocation pattern

- Initial generation, mostly at grain boundaries
- Inhomogeneous dislocation distribution on different scales
- Multiplication, pile-up and restructuring to subgrain boundaries
- Dislocation clusters with dominant influence on solar cell efficiency

ありがとうございました。



References

- K Arafune *et al*: Phys. B **376** (2006) 236.
- L Bragg, JF Nye: Proc Royal Soc Lond Ser A (1947) 474.
- O Breitenstein: Sol En Mater Sol Cells **107** (2012) 381.
- D Oriwol *et al*: Acta Mater **61** (2013) 6903.
- I Tarasov *et al*: Phys. B **273-274** (1999) 549.